



Conductive copper Pastes Portfolio overview

Aug 2022

Transforming the foundation of conductive patterns

Copprint provides conductive copper inks, enabling additive fabrication of conductive patterns.

Substituting incumbent technologies:

- Silver inks: 5-10x more expensive
- PCBs etching: hazardous, polluting, and more expensive



Backed by Top Strategics with Significant World Market Share





Electronics is a growing multi-trillion \$ market



Consumer Electronics, Industrial Equipment,
Communications, Automotive, Solar Power and more....

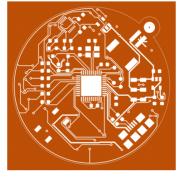
ALL electronics are powered by conductive patterns

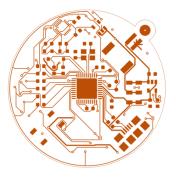


>\$70B Market Inside



Making conductive patterns: 1. Chemical etching >\$70B Mkt





Material Waste

Conductive Pattern

Chemical "cutting" of metal sheets (subtractive manufacturing)





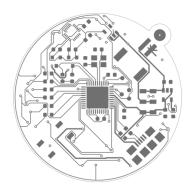
- Material Waste
- Limited Substrates
- X High Water Consumption



- X Toxic/Polluting Chemicals
- X Offshoring (90% APAC)
- Increasing Regulatory Costs

Making Conductive patterns:

- 2. Silver ink printing
- > \$3B Mkt



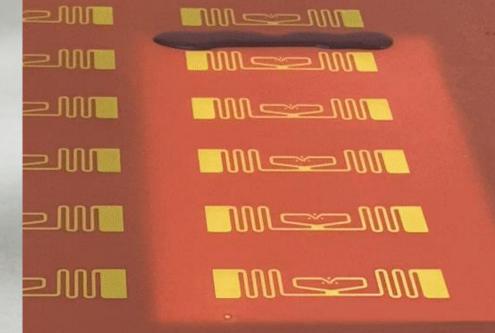
Screen printing of conductive silver inks (Additive Fabrication)



- X Prohibitively Expensive
- X Limited Adoption/Use
- X Toxic



Introducing Copprint Conductive Nano Copper inks

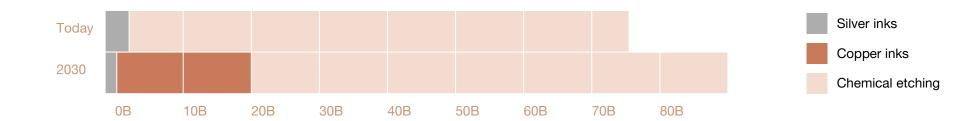


Simply print conductive patterns, using copper

The future of printed electronics is...copper

Low cost, sustainable, 'reshoring' printed circuit fabrication alternative!

Unleashing a \$70B market for additive fabrication of PCBs, antennas and photovoltaic cells...





Silver vs. Copper

Conductive silver inks are used since 100 years ago for many applications: E.g. Photovoltaics, Membrane switches, sensors, heaters and more



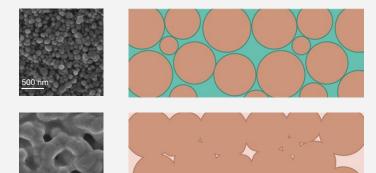
Silver is expensive and recently surged ~50% relative to its 5-years average.

Copper is a great alternative

Raw material comparison:	Silver	Copper	Copper vs Silver
Price per Kg	\$850	\$8	100X cheaper
Conductivity	1.59×10 ⁻⁸ Ωm	1.68×10 ⁻⁸ Ωm	5% less conductive
Carbon footprint	155 kgCO2/kg	3.97 kgCO2/kg	40X better
Max level in drinking water (EPA)	0.1mg/litter	1mg/litter	10X less toxic
Abundance in Earth's crust	0.08 ppm	68 ppm	~1000X more abundant



Copper Oxidation, Impeding Conductivity



Copprint Chemical Rapid Sintering

Motivation: raw copper is 100x cheaper than silver Problem: Copper oxidation prevented conductivity

Copprint

The Innovation

Copprint overcome the copper oxidation using a patented chemical sintering agent:

- Rapid low temperature Sintering which Prevents Oxidation
- Highly Conductive results
- Low Cost, Efficient (No Material Waste)
- Substrate Freedom
- Standard "Air" Printing Process & Equipment

Copper inks that outperform Silver

Anything you can print with conductive silver inks,

Copprint can do better. Faster.

At a fraction of the cost.

Copprint screen-printing pastes for a range of substrates:

LF-300 - paper substrate

LF-350 - PET substrate

LF-360 – Low temp for PET/PC

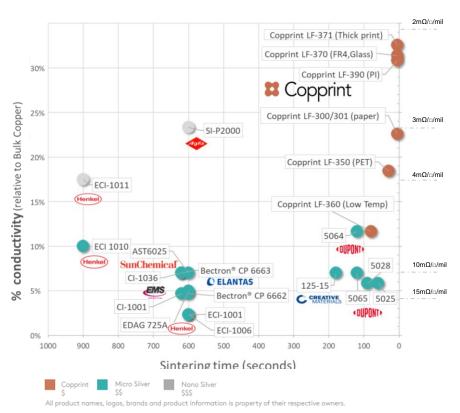
LF-370 - FR4 substrate

LF-371 – Thick printing (FR4, PV, Glass, PI)

LF-390 - Pl substrate

Additional substrates: Glass, Alumina, Aluminum, PC, PEN, CFRP, Tesline





Copprint's pastes for various substrates

Paste	Substrate	Viscosity (cPs)	Sintering Temp °C	Processing	Sheet resistance mΩ/□/25μm	Solid content
LF300	Paper	7,000	280-300	R2R	<3	83%
LF301	Paper	2,000	240-260	R2R	<3-6	81%
LF350	PET	6,000	200	S2S	<4	81%
LF360	Low-temp PET, PC	15,000	160 140	S2S + R2R	<6 <9	88%
LF370	FR4/Alumina/Glass/Aluminum	9,000	240-300	S2S + R2R	<2.3	88%
LF371	FR4/Alumina/Glass/Aluminum	30,000	240-300	S2S + R2R	<2.3	90%
LF380	HJT PV	500,000	240-300	S2S	<2.3	90%
LF390	PI	15,000	240-300	S2S + R2R	<2.3	88%



Really Simple Fabrication (Prototyping, Short Runs)

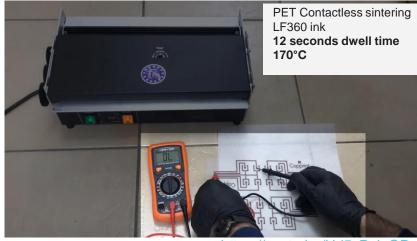
1) Print

2) Dry

3) Sinter







Screen printing in few seconds

Drying oven/conveyor/UV

Oven/Conveyor: 30-120 sec at 70-150°C

NIR/UV lamps - 1-5 seconds

https://voutu.be/Hd5vRxiaODs

Standard hot-press/contactless Laminator 140-300°C

Laminator – 3-12 sec dwell time

Hot-press - 30-240 Sectary and CONFIDENTIAL



Muhlbauer APS tailored to Copprint ink Industrial Scale Antenna Printing Solution



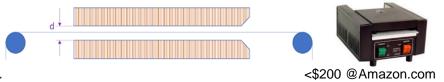
Snap heating is required for sintering

Contactless laminator:

Simple and robust system for S2S and R2R implementation.

Temperature 170°-320°C

Typical dwell time – 3-12 seconds.

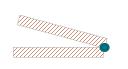


Simple hot-press (Manual or pneumatic):

Simple and robust system for S2S - Temperature 140°-300°C

No significant pressure is required – just efficient heat transfer.

Sintering of >30 sheets in parallel in a single press was tested



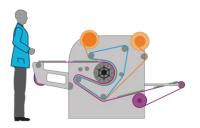




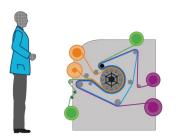


Hot roller sintering

Sheet to Sheet



Roll to Roll



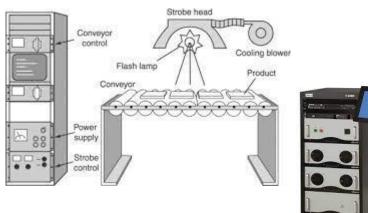


Sheet to Sheet sintering on PET @2meter/min

https://youtu.be/kYLSc9YqFQY



R2R sintering (cont)



Photonic sintering – Reported to be working well on R2R

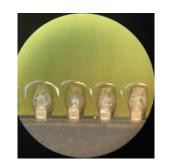
NIR sintering – In beta for R2R sintering





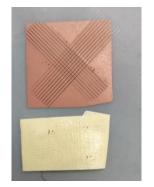
Durable printed patterns on multiple substrates

- ✓ Paper, PET, PI, Teslin, Aluminum, Alumina, FR4, Glass, PV cells
- ✓ Accelerated durability tests (90°/60%, 85°/85% tests)
- √ Excellent adhesion
- ✓ Crosshatch test 4-5b
- ✓ Bending tests (25x rolls over 5mm radius rod, <10% change).</p>
- √ Solderability





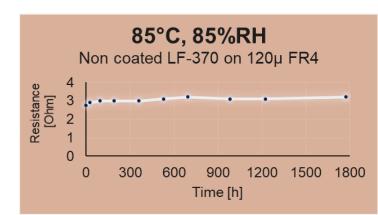
https://youtu.be/JedfsK63t



LF-350 on PET



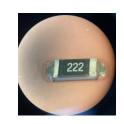
LF-370 on anodized aluminum

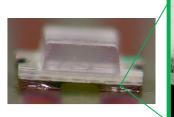


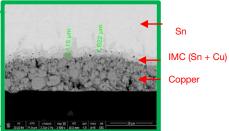


Soldering in a reflow oven (printed copper traces on FR4 & PET):

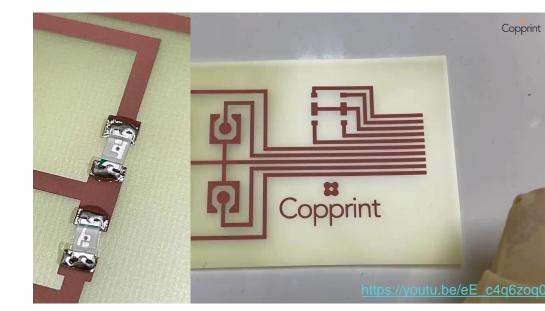
 Excellent adhesion and highquality IMC (Intermetallic compound)





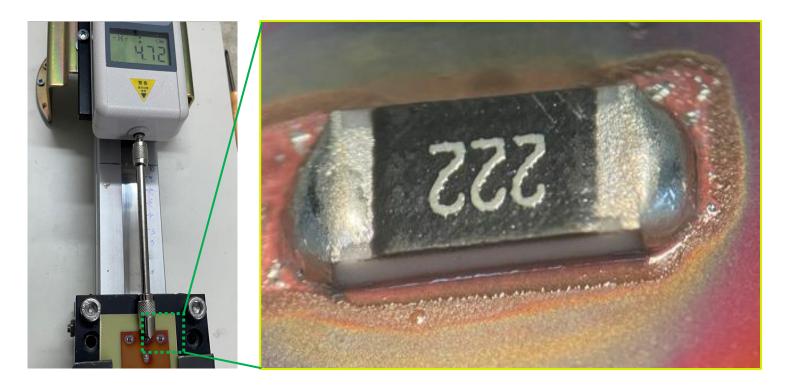


 On PET - Finally, an alternative to ECAs (electrically conductive adhesive). These ECAs are silver based and much expensive relative to soldering.





Testing soldering using die-shear





Soldering on FR4: Wetting vs. Shear force

Composition	Brand	Name	Minimal force [Kgf]	Wetting	
SAC305	Loctite	318	>3.1	OK (best)	
SAC305	AIM	M8, 88.5- T4	>4	Some dewetting	
63-37	AIM	M8 89.5-T4	>3.2	Poor (balling)	
SAC305	Shenmao	PF606- P(20-38um)	>3.7	Some dewetting	

Wetting test does not predict the shear force performance



LF-300/LF-301

Conductive copper paste for screen-printing on Paper substrate





LF 300/LF 301 – Copper paste for screen printing on a Paper substrate

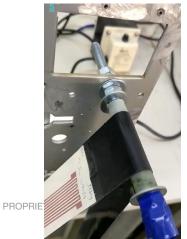
- Key usage: RFID antennas compostable RFIDs
- High conductivity
- Low cost and compostable UHF/HF/NFC RFID antennas
- Typical printing thickness for RFID antennas 3-8 micron thickness.
- Multiple durable paper approved (Verso, Mitsubishi and more).
- Accelerated durability tests (90°/60%, 85°/85% tests)
- Bending tests (25x rolls over 5mm radius rod, <10% change).
- Die-shear tests







https://youtu.be/JedfsK63t>



Partnership: Muhlbauer

- >90% of RFID manufactured using MB machines
- Custom built printer for Copprint inks - APS - available







Printed RFID antennas – on every merchandise

Printed antennas are cheaper and eco-friendly

RFID	Etched Aluminum on Plastics (PET) (>90% of the market)	Copprint Printed Nano Copper on Paper
Manufacturing	Highly polluting (China and Malaysia)	Simple printing
Turnaround	6 weeks	1 week
Tag disposal	NON recyclable: Plastics, Aluminum High volume, small pieces	Compostable, Green RFID Paper, Minimal copper traces
UHF antenna cost	0.2-0.6¢	Up to 30% cheaper (depending on geometry/volume)
NFC antenna cost	1¢	<0.4¢

20B units 2019 to 1T units by 2025





Cheaper than Etching!



LF 300/LF301 - Additional resources

- Video How to Copprint LF-300: https://youtu.be/8pDF_dUSxL0
- TDS LF300 http://copprint.com/wp-content/uploads/2020/11/TDS-LF-300.pdf
- TDS LF301 https://www.copprint.com/wp-content/uploads/2021/12/TDS-LF-301-Beta-22-08-21.pdf
- MSDS http://copprint.com/wp-content/uploads/2020/11/MSDS-rev10-LF-products.pdf
- Application notes http://copprint.com/wp-content/uploads/2020/11/Application-notes-Copprint-LF-300.pdf

- Video Who cares about the Tag? Compostable RFID antennas https://youtu.be/5S8alzlz4b0
- Video Compostable NFC antennas https://youtu.be/obncn1XtWLU



LF-370/LF-371

Conductive copper paste for screen-printing on FR4, Glass, Alumina, Aluminum...

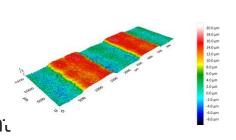




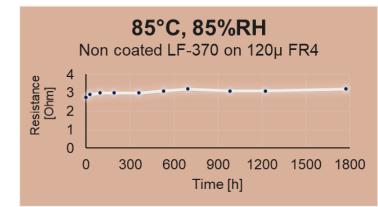
LF-370 / LF-371 - High-end Printed electronics inks

- √ ~2.2mΩ/□/mil
- √ ~5.3 µΩcm
- ✓ 85-90% solids
- ✓ Excellent 85/85 performance
- ✓ Excellent adhesion
- ✓ Crosshatch test 5b.
- ✓ Solderability
- ✓ Simple S2S and R2R implementations via contactless sintering

- ✓ FR4, Glass, Alumina, Aluminum
- ✓ LF-370 Viscosity 7,000cPs.
- ✓ LF-371 Viscosity 30,000cPs (Thick printing)
- ✓ Applications:
- ✓ One-sided / Two-sided PCBs
- ✓ LED mounts on FR4, Aluminum
- ✓ Glass printing for displays
- ✓ PV metalization

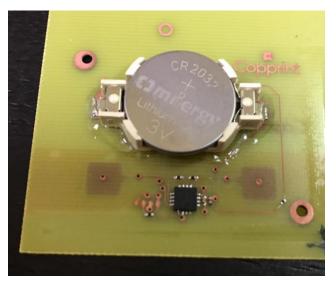


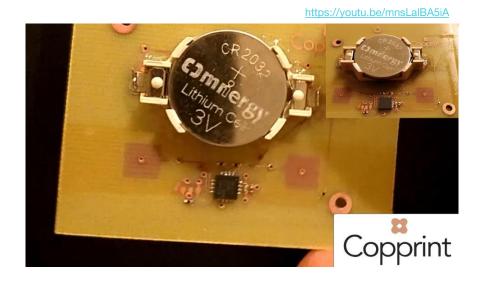




LF-370 / LF-371 – Simpler production of 1-sided and 2-sided PCBs

- Sintering via contactless sintering
- Sintering of both sides (and the via paste) together







Glass printing for LED display boards

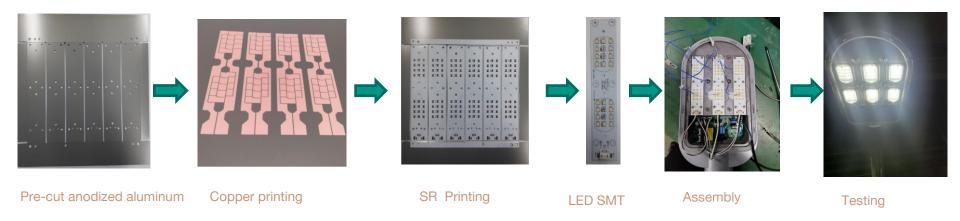
Printing on Glass for transparent glass LED display







Printed copper traces on LED aluminum baseboard







Printed copper traces on PV wafers

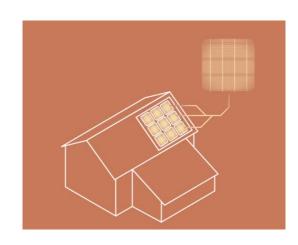
Silver inks used in PVs are made comprise 20-30% of the PV module cost

Copprint already demonstrated high-efficiency working HJT and IBC PV cells with >10% \$/watt cost saving per module!

Passing DH2000 (85°/85%, 2000 hours), TC400 (-40°:+85° x 400 cycles)

Dramatically reducing cost / Accelerating green energy sources.







LF 370/371 - Additional resources

- Video How to Copprint LF-370: https://youtu.be/CdjpUZijPg0
- TDS http://copprint.com/wp-content/uploads/2020/11/TDS-LF-370.pdf http://copprint.com/wp-content/uploads/2020/11/TDS-LF-370.pdf content/uploads/2020/11/TDS-LF-371.pdf
- MSDS http://copprint.com/wp-content/uploads/2020/11/MSDS-rev10-LF-products.pdf
- Application notes http://copprint.com/wp-content/uploads/2020/11/Application-notes-Copprint-LF370- 371.pdf
- Laminator modification guide https://www.copprint.com/wp-content/uploads/2022/03/TLC-laminatormodifications-Nov21.pdf



LF-390

Conductive copper paste for screen-printing on PI



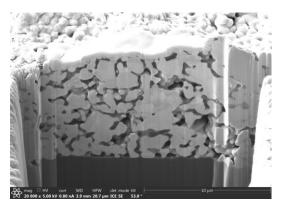


LF-390 – Conductive copper ink for PI (Polyimide)

- √ ~2.2mΩ/□/mil
- \checkmark ~5.3 μΩcm
- ✓ LF-390 Viscosity 15000cPs
- √ 85-90% solids
- ✓ Excellent 85°/85% performance
- ✓ Excellent adhesion and flexibility
- ✓ Simple S2S and R2R implementations via contactless sintering

Applications:

- √ Sensors
- √ Flexible PCBs
- √ Connectors



Cross-section after sintering



LF 390 - Additional resources

- Video How to Copprint LF-390 same video as LF-370: https://youtu.be/CdjpUZjjPg0
- TDS http://copprint.com/wp-content/uploads/2020/11/TDS-LF-390.pdf
- MSDS http://copprint.com/wp-content/uploads/2020/11/MSDS-rev10-LF-products.pdf
- Application notes http://copprint.com/wp-content/uploads/2021/02/Application-notes-Copprint-LF390.pdf



LF-350

Conductive copper paste for screen-printing on PET





LF-350 – Conductive copper ink for PET

- √ ~4mΩ/□/mil
- ✓ LF-350 Viscosity 5000cPs
- ✓ Excellent adhesion and flexibility
- ✓ Solderability
- ✓ Simple, high throughput S2S process
- ✓ R2R via photonic sintering (tested), hot-roller and NIR (beta)

Applications:

- √ Heaters
- ✓ Membrane-switches
- √ Sensors
- ✓ Antennas





Automotive Silver heaters vs Copper heaters

- Seat heater
- Interior panel heater
- Battery Heater
- Technical heater

Same design

Same electrical properties

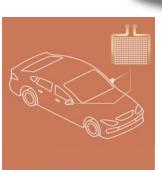
Same performance

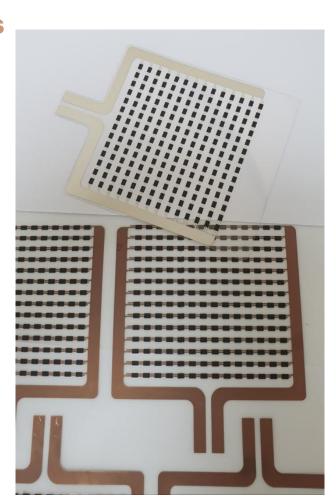
5-10x cheaper











LF 350 - Additional resources

- Video How to Copprint LF-350 https://youtu.be/0chiF8vVGFY
- TDS http://copprint.com/wp-content/uploads/2020/11/TDS-LF-350.pdf
- MSDS http://copprint.com/wp-content/uploads/2020/11/MSDS-rev10-LF-products.pdf
- Application notes http://copprint.com/wp-content/uploads/2021/01/Application-notes-Copprint-LF350.pdf



LF-360

Conductive copper paste for low temp sintering on PET/PC



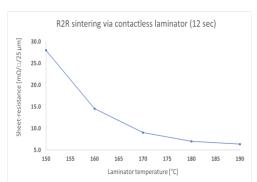


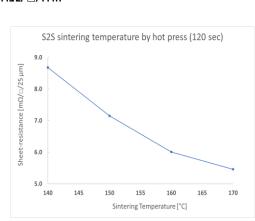
LF-360 – low-temp sintering

- ~6mΩ/□/mil
- ✓ PET and PC
- ✓ LF-360 Viscosity 15,000cPs
- ✓ Excellent adhesion and flexibility
- ✓ Solderability
- ✓ Simple, high throughput S2S process 60-120 seconds using a heat-press 140°C-160°C
- ✓ R2R:
 - Contact-less laminator (between two hot plates) 12 seconds @170°C -> ~9mΩ/□/mil
 - photonic sintering
 - NIR

Applications:

- √ Heaters
- ✓ R&R underfloor heaters
- ✓ Membrane-switches
- ✓ Sensors
- ✓ Antennas







LF 360 - Additional resources

- Video How to Copprint LF-360 https://youtu.be/90IQMHJWf50
- TDS http://copprint.com/wp-content/uploads/2021/03/TDS-LF-360-draft-3-3-21.pdf
- MSDS http://copprint.com/wp-content/uploads/2021/03/MSDS-rev11-LF-products.pdf
- Application notes: http://copprint.com/wp-content/uploads/2021/03/Application-notes-Copprint-LF360- draft.pdf
- Video sintering using a hot-roller: https://youtu.be/kYLSc9YqFQY



Copprint

Thank you.

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